

APPLICATIONS

- Rectification
- Freewheel Diode
- DC Motor Control
- Power Supplies
- Welding
- Battery Chargers

FEATURES

- High Surge Capability

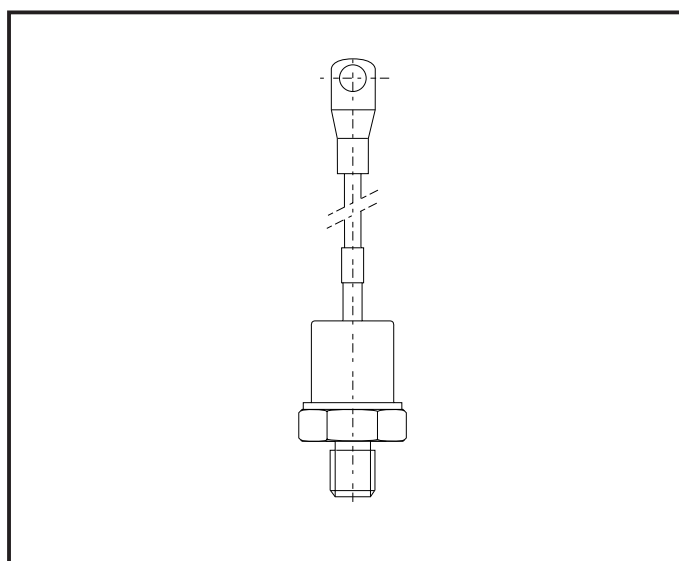
VOLTAGE RATINGS

Type Number	Repetitive Peak Reverse Voltage V_{RRM} V	Conditions
TV30 20 M or K(R)	2000	$V_{RSM} = V_{RRM} + 100V$
TV30 14 M or K(R)	1400	
TV30 10 M or K(R)	1000	
TV30 06 M or K(R)	600	

Lower voltage grades available.
M for M16 thread. K for 3/4" - 16UNF thread, R for reverse polarity.

KEY PARAMETERS

V_{RRM}	2000V
$I_{F(AV)}$	335A
I_{FSM}	6000A



Outline type code: DO9
See Package Details for further information.

CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
Single Side Cooled				
$I_{F(AV)}$	Mean forward current	Half wave resistive load, $T_{case} = 100^{\circ}C$	335	A
$I_{F(RMS)}$	RMS value	$T_{case} = 100^{\circ}C$	525	A
I_F	Continuous (direct) forward current	$T_{case} = 100^{\circ}C$	440	A

SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; $T_{case} = 175^{\circ}C$ $V_R = 50\% V_{RRM} - 1/4$ sine	4.8	kA
I^2t	I^2t for fusing		115×10^6	A ² s
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; $T_{case} = 175^{\circ}C$ $V_R = 0$	6.0	kA
I^2t	I^2t for fusing		180×10^3	A ² s

THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case	dc	-	0.13	°C/W
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Mounting torque 35.0Nm with mounting compound	-	0.06	°C/W
T_{vj}	Virtual junction temperature	Forward (conducting)	-	175	°C
		Reverse (blocking)	-	175	°C
T_{stg}	Storage temperature range		-55	200	°C
-	Mounting Torque		30.0	35.0	Nm

CHARACTERISTICS

Symbol	Parameter	Conditions	Typ.	Max.	Units
V_{FM}	Forward voltage	At 1000A peak, $T_{case} = 25^{\circ}C$	-	1.4	V
I_{RRM}	Peak reverse current	At V_{RRM} , $T_{case} = 175^{\circ}C$	-	20	mA
Q_S	Total stored charge	$I_F = 200A$, $di_{RR}/dt = 20A/\mu s$, $T_{case} = 25^{\circ}C$	300*	-	μC
I_{RM}	Peak recovery current		90*	-	A
t_{rr}	reverse recovery time		6.5*	-	μs
V_{TO}	Threshold voltage	At $T_{vj} = 175^{\circ}C$	-	0.8	V
r_T	Slope resistance	At $T_{vj} = 175^{\circ}C$	-	0.6	m Ω

*Typical values.

CURVES

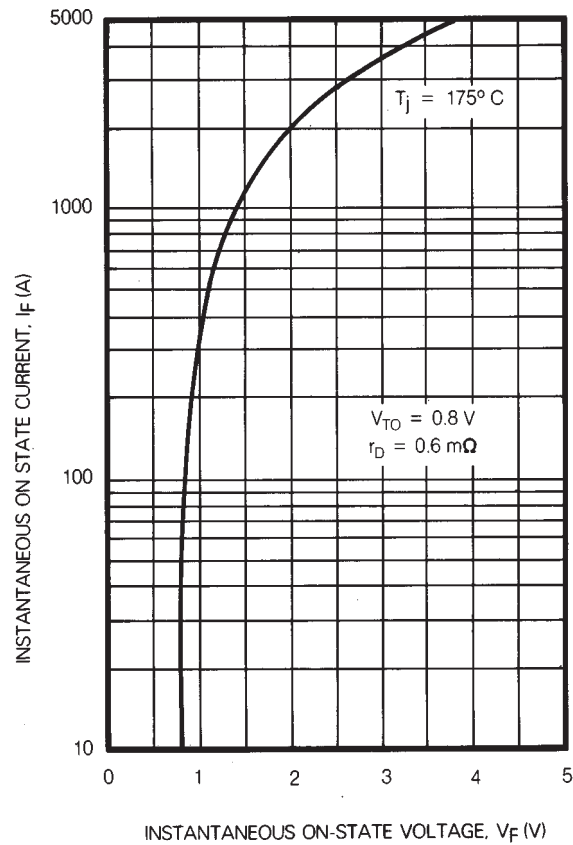


FIG. 1 MAXIMUM (LIMIT) FORWARD CONDUCTION CHARACTERISTIC

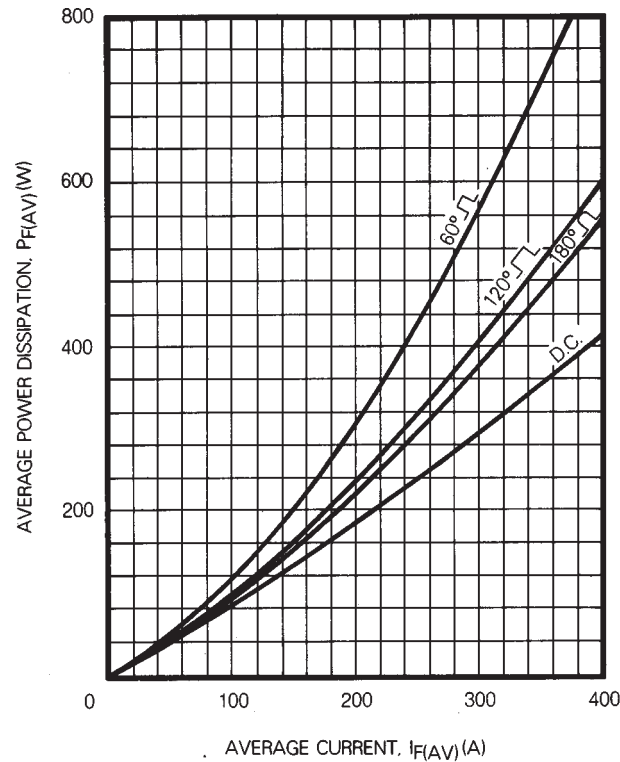


FIG. 2 MAXIMUM FORWARD POWER DISSIPATION

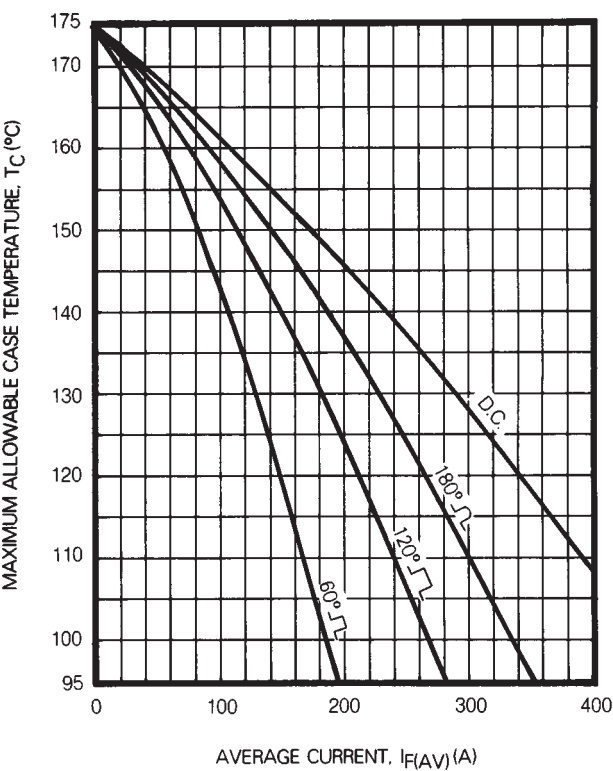


FIG. 3 MAXIMUM ALLOWABLE CASE TEMPERATURE

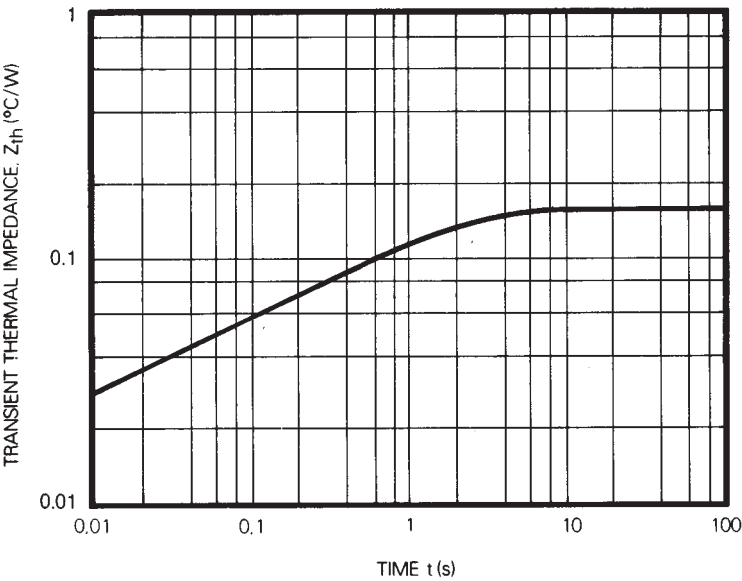
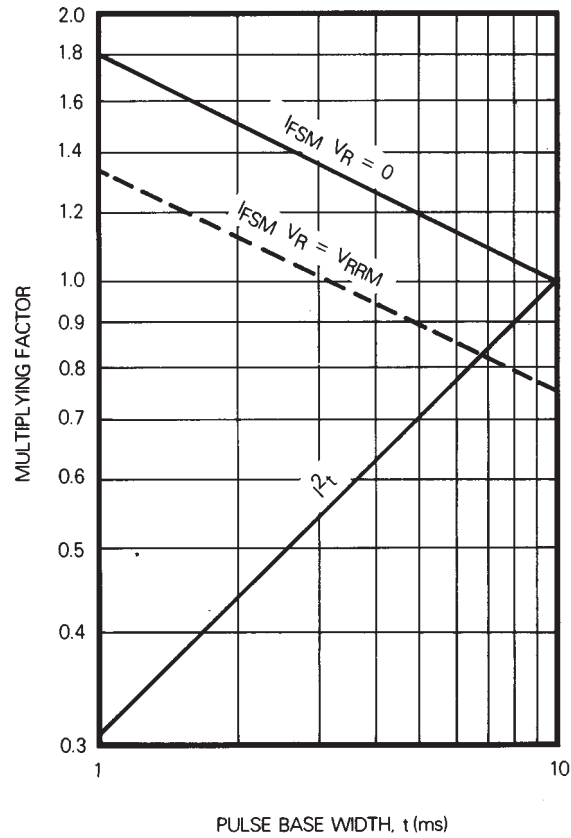
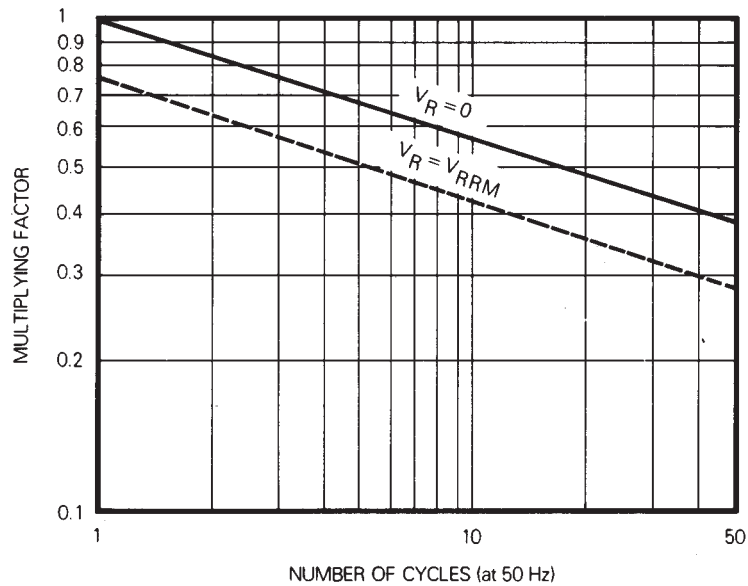


FIG. 4 TRANSIENT THERMAL IMPEDANCE - JUNCTION TO CASE

Conduction angle	Effective thermal Resistance ($^{\circ}\text{C/W}$) Junction to case	
	Sinusoidal	Rectangular
180°	0.173	0.192
120°	0.179	0.216
60°	0.208	0.272



**FIG. 5 MULTIPLYING FACTOR FOR
NON-REPETITIVE SUB-CYCLE FORWARD
CURRENT AND I_2t RATING**

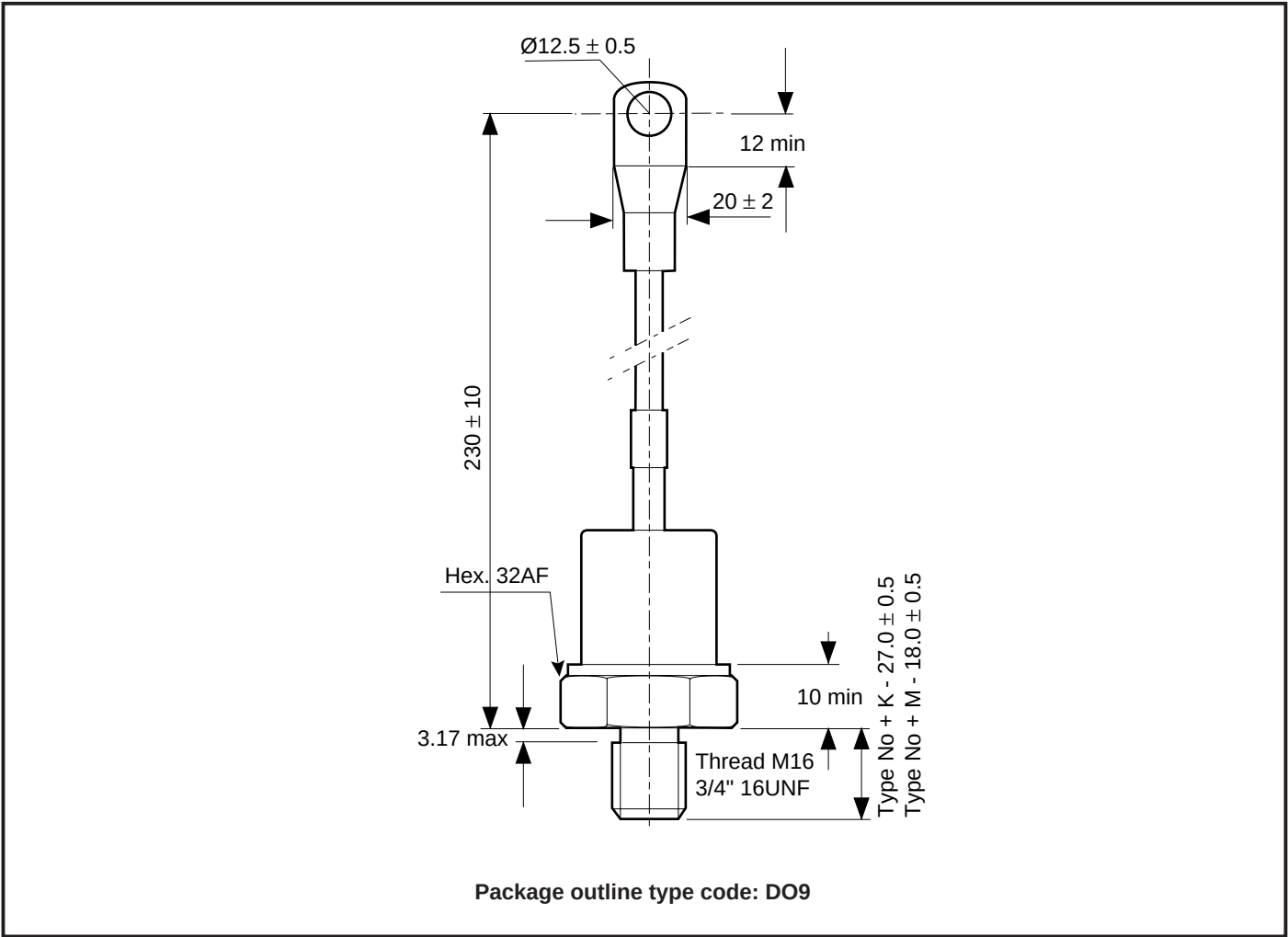


**FIG. 6 MULTIPLYING FACTOR FOR NON-REPETITIVE
FORWARD CURRENT**

TV30

PACKAGE DETAILS

For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



ASSOCIATED PUBLICATIONS

Title	Application Note
	Number
Calculating the junction temperature or power semiconductors	AN4506
Thyristor and diode measurement with a multi-meter	AN4853
Use of V_{TO} , r_T on-state characteristic	AN5001

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group continues to offer high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the up to date CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete solution (PACs).

HEATSINKS

Power Assembly has its own proprietary range of extruded aluminium heatsinks. They have been designed to optimise the performance of our semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest Sales Representative or the factory.



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Target Information: This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

Advance Information: The product design is complete and final characterisation for volume production is well in hand.

No Annotation: The product parameters are fixed and the product is available to datasheet specification.

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